Product Change Notification: MFOL-26TLSM249

Date:

23-Oct-2026

Product Category:

USB Hubs

Notification Subject:

CCB 8064 Final Notice: Qualification of MTAI as an additional assembly site for USB7052NT/KDX, USB7002T-I/KDX, USB7006T-I/KDX, USB7016T-I/KDX, USB7052NT-I/KDX, USB7002/KDX, USB7052N/KDX, USB7002-I/KDX, USB7006-I/KDX, USB7016-I/KDX, USB7052N-I/KDX, USB7002T/KDX, USB7006/KDX, USB7006T/KDX, USB7016T/KDX, USB7016/KDX, USB7050P/KDX, USB7050P-I/KDX, USB7050PT/KDX and USB7050PT-I/KDX catalog part numbers (CPN) available in 100L VQFN (12X12X0.9mm) package.

Affected CPNs:

MFOL-26TLSM249_Affected_CPN_10232026.pdf
MFOL-26TLSM249_Affected_CPN_10232026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for USB7052NT/KDX, USB7002T-I/KDX, USB7006T-I/KDX, USB7016T-I/KDX, USB7052NT-I/KDX, USB7002/KDX, USB7052N/KDX, USB7002-I/KDX, USB7006-I/KDX, USB7016-I/KDX, USB7052N-I/KDX, USB7002T/KDX, USB7006/KDX, USB7006T/KDX, USB7016T/KDX, USB7016/KDX, USB7050P/KDX, USB7050P-I/KDX, USB7050PT/KDX and USB7050PT-I/KDX catalog part numbers (CPN) available in 100L VQFN (12X12X0.9mm) package.

Pre and Post Summary Changes:

	Pre Change		Post Change			Change (Yes/No)
Assembly Site	ASE Inc. (ASE)	ASE Group Chung-Li (ASCL)	ASE Inc. (ASE)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (HQ) (MTAI)	Yes
Wire Material	CuPdAu	CuPdAu	CuPdAu	CuPdAu	CuPdAu	No
Die Attach Material	EN-4900F (PFAS-Free)	EN-4900G (PFAS-Free)	EN-4900F (PFAS-Free)	EN-4900G (PFAS-Free)	QMI519 (PFAS-Free)	Yes
Molding Compound Material	G631H	G700LA	G631H	G700LA	G700LTD	Yes
Lead-Frame Material	C194	C7025	C194	C7025	EFTEC64T	Yes
Lead-Frame Design	See 'Pre and Post Change Summary' attachment for comparison.					

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 November 2026 (date code: 2649)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2026					>	October 2026					November 2026				
Work Week	10	11	12	13	14		40	41	42	43	44	45	46	47	48	49
Initial PCN Issue Date	X															
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date																X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

March 03, 2026: Issued initial notification.
October 23, 2026: Issued final notification. Updated the 'Pre and Post Table' to add another row for 'Lead-Frame Design'. Attached the Qualification Report. Provided estimated first ship date to be on November 30, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-26TLSM249_Pre and Post Change Summary.pdf
PCN_MFOL-26TLSM249_Qualification_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

MFOL-26TLSM249 - CCB 8064 Final Notice: Qualification of MTAI as an additional assembly site for USB7052NT/KDX, USB7002T-I/KDX, USB7006T-I/KDX, USB7016T-I/KDX, USB7052NT-I/KDX, USB7002/KDX, USB7052N/KDX, USB7002-I/KDX, USB7006-I/KDX, USB7016-I/KDX, USB7052N-I/KDX, USB7002T/KDX, USB7006/KDX, USB7006T/KDX, USB7016T/KDX, USB7016/KDX, USB7050P/KDX, USB7050P-I/KDX,

Affected Catalog Part Numbers (CPN):

USB7050P-I/KDX

USB7050PT/KDX

USB7050PT-I/KDX

USB7052NT/KDX

USB7002T-I/KDX

USB7006T-I/KDX

USB7016T-I/KDX

USB7052NT-I/KDX

USB7002/KDX

USB7052N/KDX

USB7002-I/KDX

USB7006-I/KDX

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USB7052N-I/KDX

USB7002T/KDX

USB7006/KDX

USB7006T/KDX

USB7016T/KDX

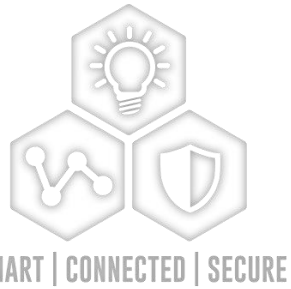
USB7016/KDX

USB7050P/KDX

CCB 8064
Pre and Post Change Summary
PCN #: MFOL-26TLSM249



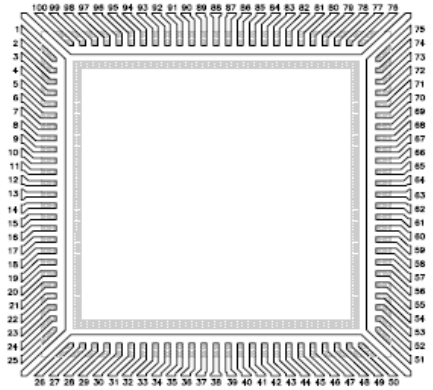
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



Pre and Post Change – Lead Frame Design

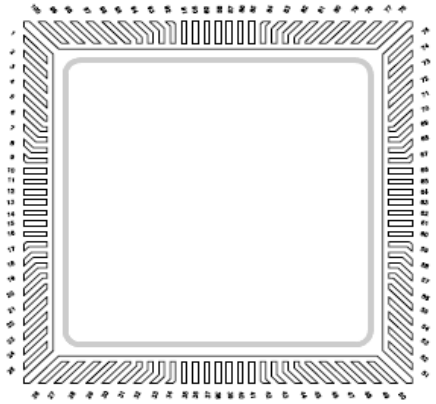
Pre Change

ASCL



Lead-Frame Material	C7025

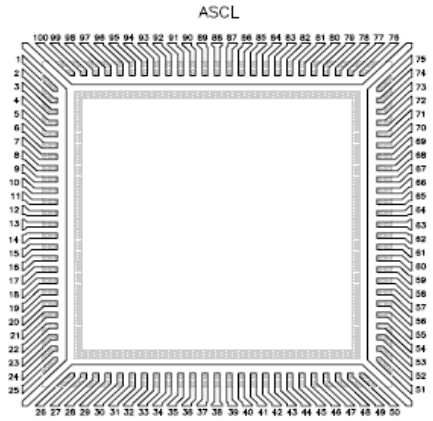
ASE



Lead-Frame Material	C194

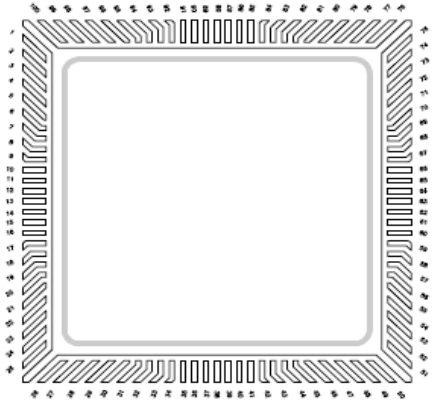
Post Change

ASCL



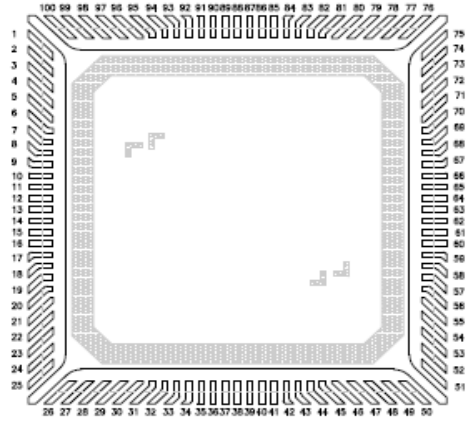
Lead-Frame Material	C7025

ASE



Lead-Frame Material	C194

MTAI



Lead-Frame Material	EFTEC64T

Note: *Not For Scale

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Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MFOL-26TLSM249

Date:
September 29, 2026

Qualification of MTAI as an additional assembly site for USB7052NT/KDX, USB7002T-I/KDX, USB7006T-I/KDX, USB7016T-I/KDX, USB7052NT-I/KDX, USB7002/KDX, USB7052N/KDX, USB7002-I/KDX, USB7006-I/KDX, USB7016-I/KDX, USB7052N-I/KDX, USB7002T/KDX, USB7006/KDX, USB7006T/KDX, USB7016T/KDX, USB7016/KDX, USB7050P/KDX, USB7050P-I/KDX, USB7050PT/KDX and USB7050PT-I/KDX catalog part numbers (CPN) available in 100L VQFN (12X12X0.9mm) package. This is a Q006 Grade 3 Qualification.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MTAI as an additional assembly site for USB7052NT/KDX, USB7002T-I/KDX, USB7006T-I/KDX, USB7016T-I/KDX, USB7052NT-I/KDX, USB7002/KDX, USB7052N/KDX, USB7002-I/KDX, USB7006-I/KDX, USB7016-I/KDX, USB7052N-I/KDX, USB7002T/KDX, USB7006/KDX, USB7006T/KDX, USB7016T/KDX, USB7016/KDX, USB7050P/KDX, USB7050P-I/KDX, USB7050PT/KDX and USB7050PT-I/KDX catalog part numbers (CPN) available in 100L VQFN (12X12X0.9mm) package. This is a Q006 Grade 3 Qualification.

QUAL ID:	R2600362 (Rev. A)
MP CODE:	STB127KDXVM1
Part No.:	USB7002-I/KDXVAO
Bonding No.:	BD-003969
CCB No.:	8064

Lead Frame

Paddle Size:	323x323
Material:	EFTEC64T
DAP Surface Prep:	Ag ring plated
Process:	Etched
Lead Lock:	No
Part Number:	10110011
Lead Plating:	Matte Tin
LF Treatment:	Roughening
Strip Size:	70 x 250 mm
Strip Density:	240 units/strip

Bond Wire

Wire:	CuPdAu

Die Attach Material

Epoxy:	QMI519
Conductive:	Yes

Mold Compound

Mold Compound:	G700LTD

Package

Type:	VQFN
Package Size:	12x12x0.9 mm
Package Lead Count:	100

Manufacturing Information

Assembly Lot No.
MTAI264600302.000
MTAI264601163.000
MTAI264601172.000

Conclusion:

Qualification of STB12 mask / USB7002-I/KDXVAO product / CuPdAu wire in 100L VQFN 12x12x0.9 mm package at MTAI site is qualified for MSL3 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance with Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture Soak Precondition Prior to Stresses	**MSL3:** 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 260°C Electrical Test **Tester:** LTX_D1X_MP1X 25°C and 105°C	JESD22-A113 , JEDEC J-STD-020	231 units each lot / 3 lots	0/231, 0/231, 0/231	Pass	Lots: MTAI264600302.000, MTAI264601163.000, MTAI264601172.000
High Temp Storage	150°C / 500 hours Electrical Test **Tester:** LTX_D1X_MP1X 25°C and 105°C	JESD22-A103	45 units each lot / 3 lots	0/45, 0/45, 0/45	Pass	Lots: MTAI264600302.000, MTAI264601163.000, MTAI264601172.000
Temperature Cycling	-55°C / +125°C Air to Air / 500 Cycles Electrical Test **Tester:** LTX_D1X_MP1X 25°C and 105°C	JESD22-A104	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	Lots: MTAI264600302.000, MTAI264601163.000, MTAI264601172.000
Unbiased HAST	+110°C / 85%RH / 264 hours Electrical Test **Tester:** LTX_D1X_MP1X 25°C	JESD22-A118	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	Lots: MTAI264600302.000, MTAI264601163.000, MTAI264601172.000
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass	
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass	
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q100-001	5 units / 1 lot	0/5	Pass	